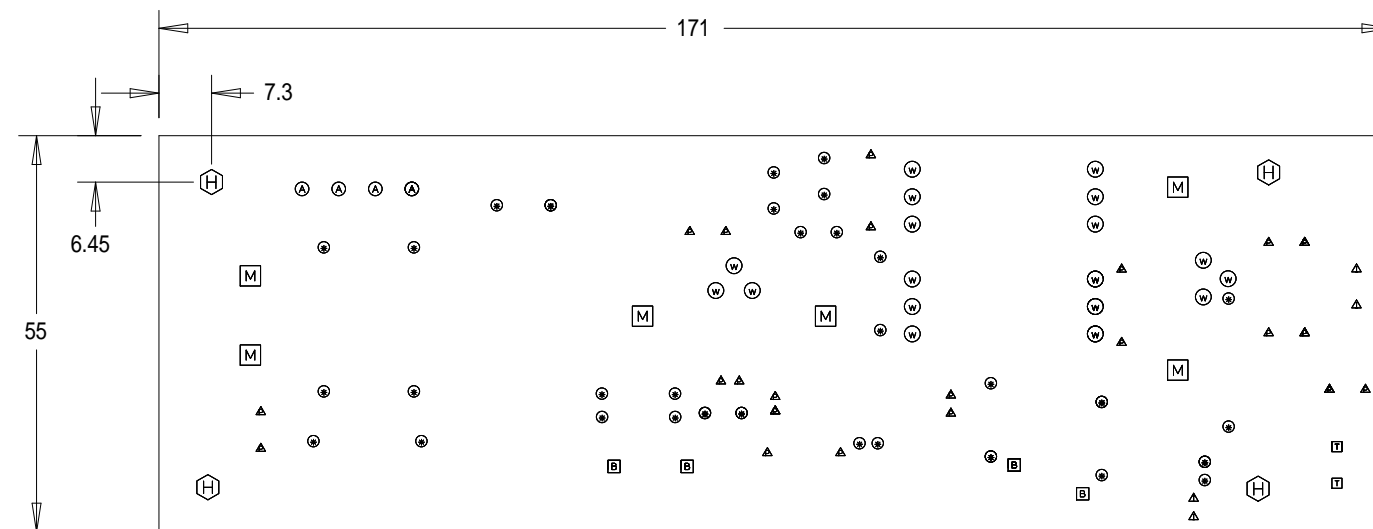


SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE


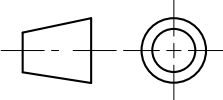
MATERIAL	FR4 IMPROVED (low CTE)		
BOARD THICKNESS		1.6mm /63mils	
STACKUP	SF /1LAYERS		
MINIMAL GAP		210um /8.0mils	
MINIMAL SLIVER		210um /8.0mils	
COPPER THICKNESS		70um(2oz)at START	
FINISH THICKNESS	CHEMICAL NiAu		
SOLDER MASK		GREEN BOT	
SILKSCREEN	WHITE TOP&BOT		
ALL BOARD ELECTRICALLY TESTED			
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK			



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILLIMETERS

FIGURE	SIZE	PLATED	QTY
▲	0.8		22
▲	0.9		4
⊙	1.0		32
⊞	1.1		4
⊞	1.4		2
⊙	1.65		18
⊙	1.9		4
⊞	2.8		6
⊞	4.0		4

2.0	W49/2014 W27/2014	
indice	Description	Date
Controle par :		Autorise par:
 ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE 
Board: <b>EVB NCP1256</b>		Subc. <b>DYPE TECH</b>
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